

# INTERNATIONAL STANDARD

# NORME INTERNATIONALE



**Packaging of components for automatic handling –  
Part 3: Packaging of surface mount components on continuous tapes**

**Emballage de composants pour opérations automatisées –  
Partie 3: Emballage des composants pour montage en surface en bandes  
continues**



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**PACKAGING OF COMPONENTS FOR AUTOMATIC HANDLING –****Part 3: Packaging of surface mount components  
on continuous tapes**

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IEC 60286-3 has been prepared by IEC technical committee 40: Capacitors and resistors for electronic equipment. It is an International Standard.

This seventh edition cancels and replaces the sixth edition published in 2019. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition terms and definitions.
- b) addition of a table of the classification to symbols concerning drive hole diameter and distance between the reel hole centre and the drive hole centre;
- c) addition of drive hole to the reel (optional);
- d) revision of reel hole diameter tolerances;
- e) revision of 72 mm tape size carrier tape width dimension tolerances;

- f) addition of Annex B (informative);
- g) addition of component size 0201M.

The text of this International Standard is based on the following documents:

|              |                  |
|--------------|------------------|
| Draft        | Report on voting |
| 40/2972/FDIS | 40/2984/RVD      |

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

A list of all parts in the IEC 60268 series, published under the general title *Packaging of components for automatic handling*, can be found on the IEC website.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at [www.iec.ch/members\\_experts/refdocs](http://www.iec.ch/members_experts/refdocs). The main document types developed by IEC are described in greater detail at [www.iec.ch/publications](http://www.iec.ch/publications).

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## INTRODUCTION

Tape packaging meets the requirements of automatic component placement machines and also covers the use of tape packaging for components and singulated dies for test purposes and other operations.